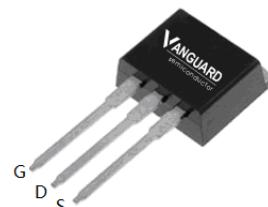


Features

- N-Channel, 5V Logic Level Control
- Enhancement mode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=4.5$ V
- Fast Switching
- 100% Avalanche test
- Pb-free lead plating; RoHS compliant

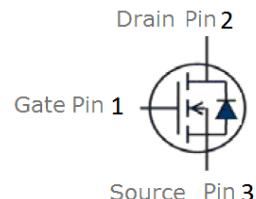
V_{DS}	60	V
$R_{DS(on),TYP}$ @ $V_{GS}=10$ V	5.0	$\text{m}\Omega$
$R_{DS(on),TYP}$ @ $V_{GS}=4.5$ V	6.0	$\text{m}\Omega$
I_D	85	A

TO-251



Halogen-Free

Part ID	Package Type	Marking	Tape and reel information
VSI007N06MS	TO-251	007N06M	75pcs/Tube



Maximum ratings, at $T_j=25$ °C, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings (Tc=25°C Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	±20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	60	V	
T_J	Maximum Junction Temperature	175	°C	
T_{STG}	Storage Temperature Range	-55 to 175	°C	
I_S	Diode Continuous Forward Current	$T_c=25^\circ\text{C}$	A	
Mounted on Large Heat Sink				
I_D	Continuous Drain current@ $V_{GS}=10$ V	$T_c=25^\circ\text{C}$	85	A
		$T_c=100^\circ\text{C}$	55	A
I_{DM}	Pulse Drain Current Tested ①	$T_c=25^\circ\text{C}$	300	A
P_D	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	100	W
R_{JJC}	Thermal Resistance-Junction to Case	1.5	°C/W	
R_{JJA}	Thermal Resistance Junction-Ambient	52.5	°C/W	
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed ②	93	mJ	

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_c = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	60	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=60\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=60\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	1.2	1.6	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=10\text{V}$, $I_D=30\text{A}$	--	5.0	7.0	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	--	6.0	9.0	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_c = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	--	3485	--	pF
C_{oss}	Output Capacitance		--	370	--	pF
C_{rss}	Reverse Transfer Capacitance		--	275	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=24\text{V}$, $I_D=10\text{A}$, $V_{\text{GS}}=10\text{V}$	--	82	--	nC
Q_{gs}	Gate-Source Charge		--	13	--	nC
Q_{gd}	Gate-Drain Charge		--	17	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=30\text{V}$, $I_D=5\text{A}$, $R_G=6.8\Omega$, $V_{\text{GS}}=10\text{V}$	--	26	--	nS
t_r	Turn-on Rise Time		--	125	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	58	--	nS
t_f	Turn-Off Fall Time		--	112	--	nS
Source- Drain Diode Characteristics@ $T_c = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{sd}}=30\text{A}$, $V_{\text{GS}}=0\text{V}$	--	0.83	1.2	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}$, $I_{\text{sd}}=10\text{A}$, $V_{\text{GS}}=0\text{V}$ $dI/dt=100\text{A}/\mu\text{s}$	--	38	--	nS
Q_{rr}	Reverse Recovery Charge		--	44	--	nC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by $T_{j\text{max}}$, starting $T_j = 25^\circ\text{C}$, $L = 0.3\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 25\text{A}$, $V_{GS} = 10\text{V}$. Part not recommended for use above this value
- ③ Pulse width $\leq 300\mu\text{s}$; duty cycles $\leq 2\%$.

Typical Characteristics

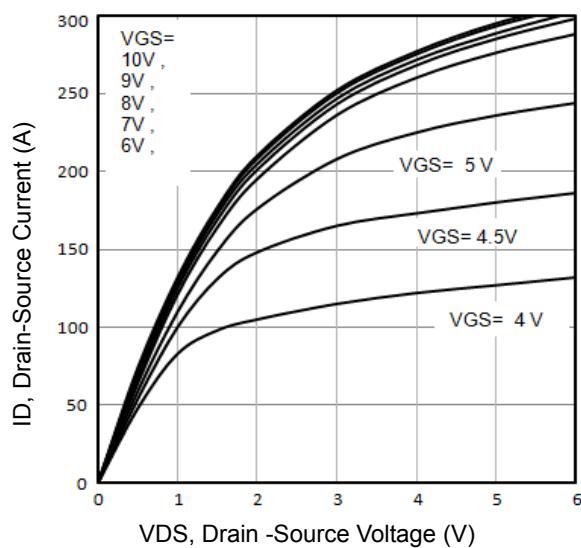


Fig1. Typical Output Characteristics

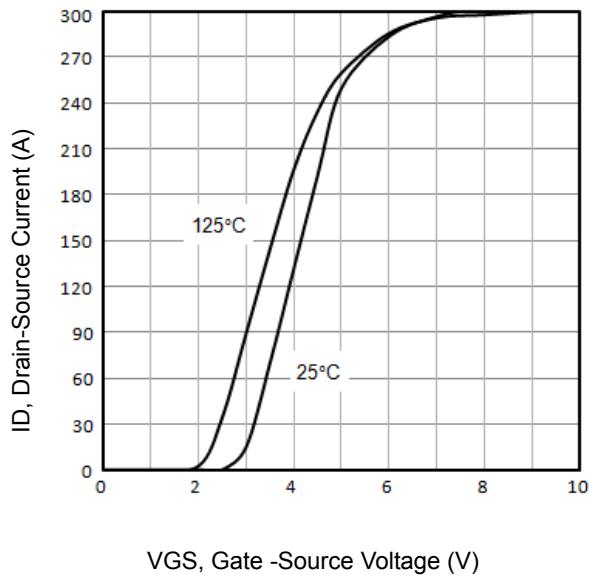


Fig3. Typical Transfer Characteristics

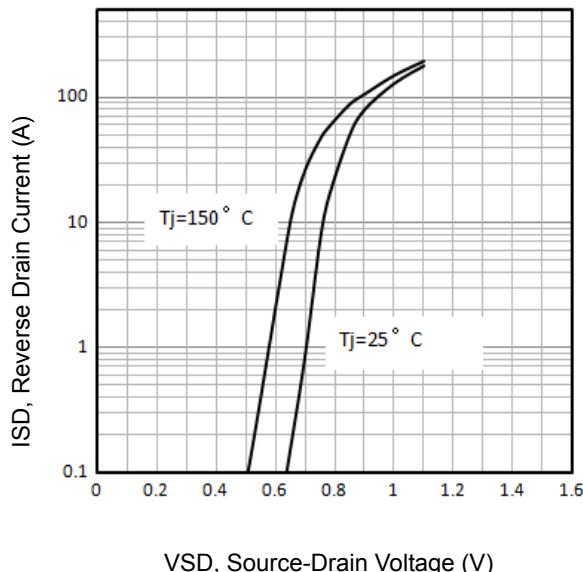


Fig5. Typical Source-Drain Diode Forward Voltage

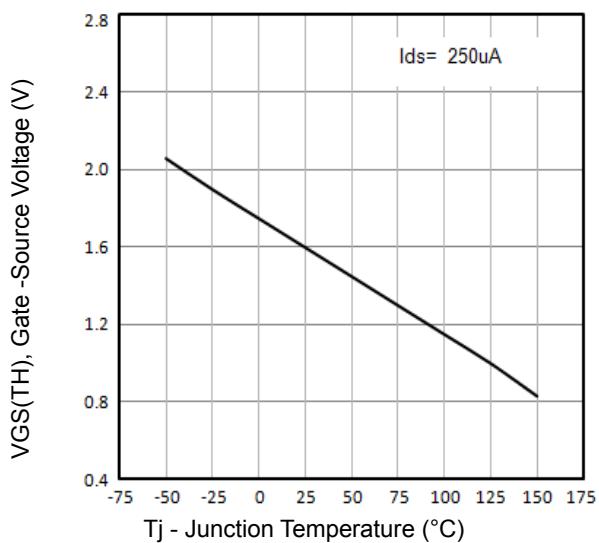


Fig2. $V_{GS(TH)}$ Gate -Source Voltage Vs.Tj

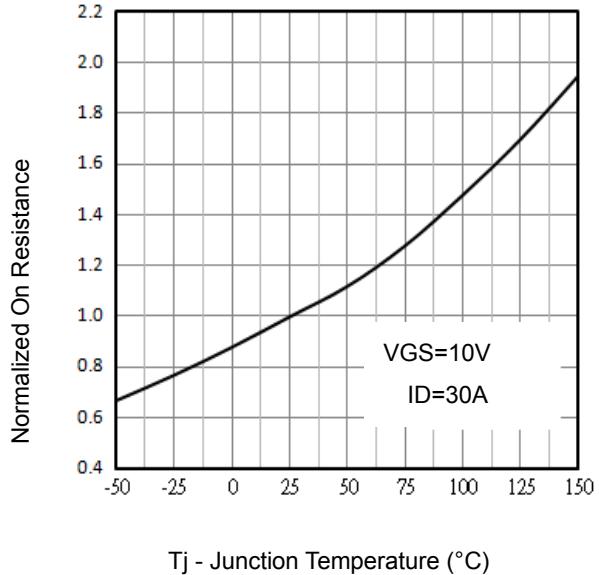


Fig4. Normalized On-Resistance Vs. Temperature

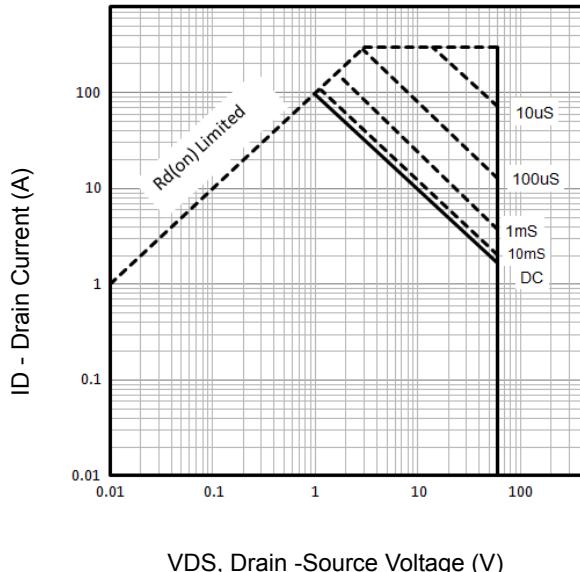
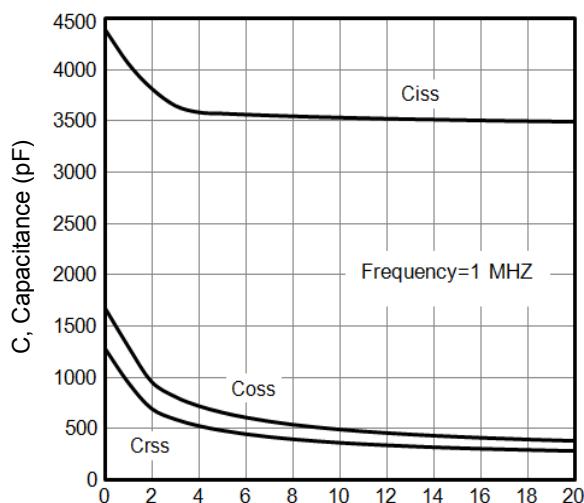


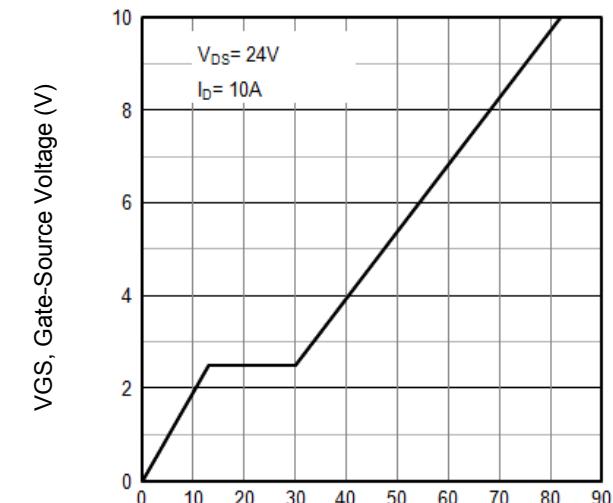
Fig6. Maximum Safe Operating Area

Typical Characteristics



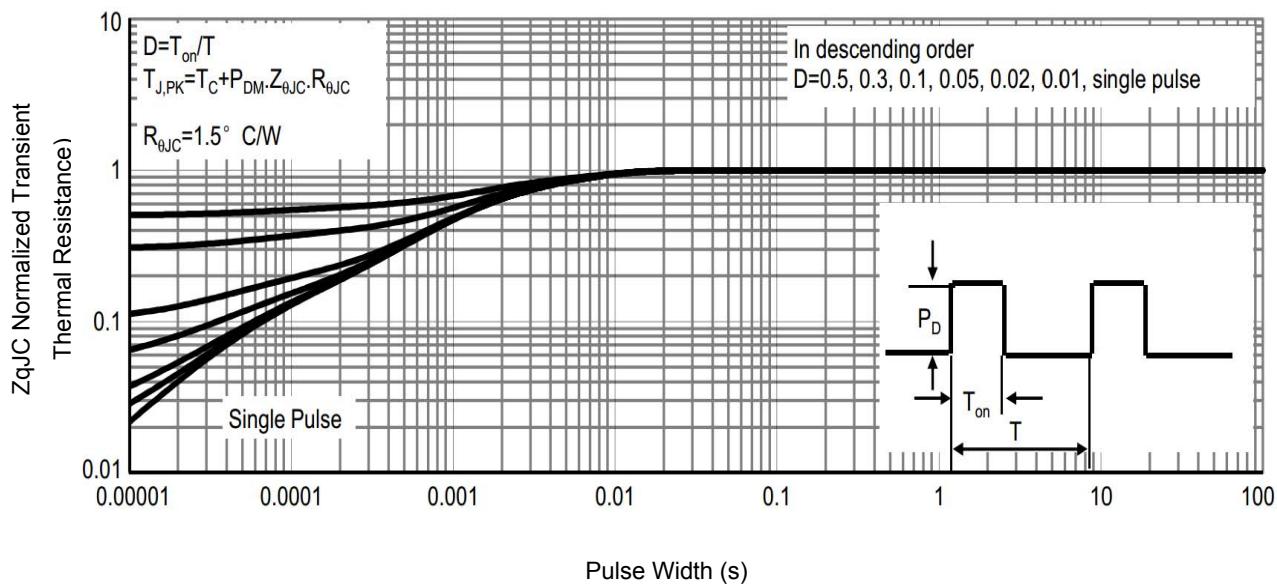
V_{DS} , Drain-Source Voltage (V)

Fig7. Typical Capacitance Vs.Drain-Source Voltage



Q_g - Total Gate Charge (nC)

Fig8. Typical Gate Charge Vs.Gate-Source Voltage



Pulse Width (s)

Fig9. Normalized Maximum Transient Thermal Impedance

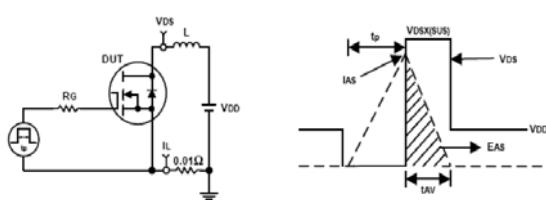


Fig10. Unclamped Inductive Test Circuit and waveforms

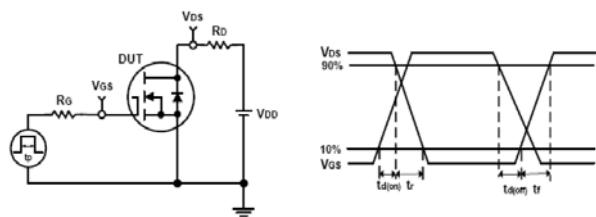
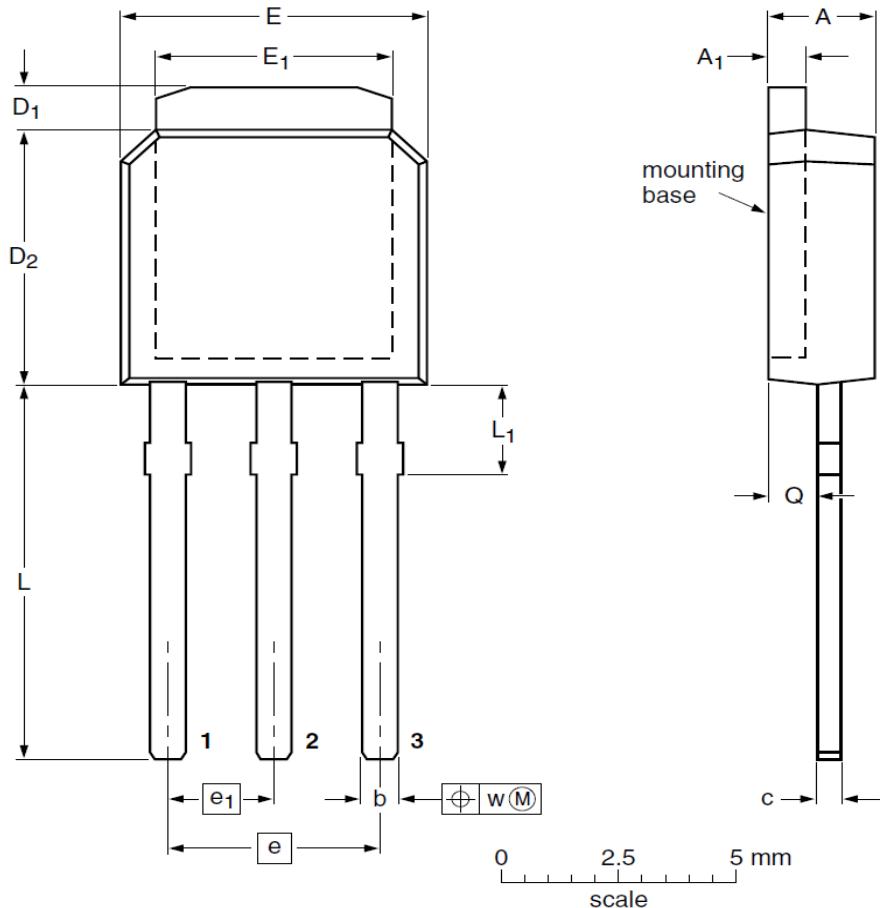


Fig11. Switching Time Test Circuit and waveforms

TO-251 Package Outline Data



DIMENSIONS (unit : mm)

Label	Min	Typ	Max	Label	Min	Typ	Max
A	2.22	2.30	2.38	A ₁	0.46	0.55	0.93
b	0.71	0.78	0.89	c	0.46	0.51	0.56
D ₁	0.96	1.02	1.10	D ₂	5.98	6.05	6.22
E	6.47	6.60	6.73	E ₁	5.20	5.33	5.55
e	--	4.57	--	e ₁	--	2.28	--
L	9.20	9.38	9.60	L ₁	--	2.70	--
Q	1.00	1.05	1.10	w	--	0.30	--

Customer Service

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